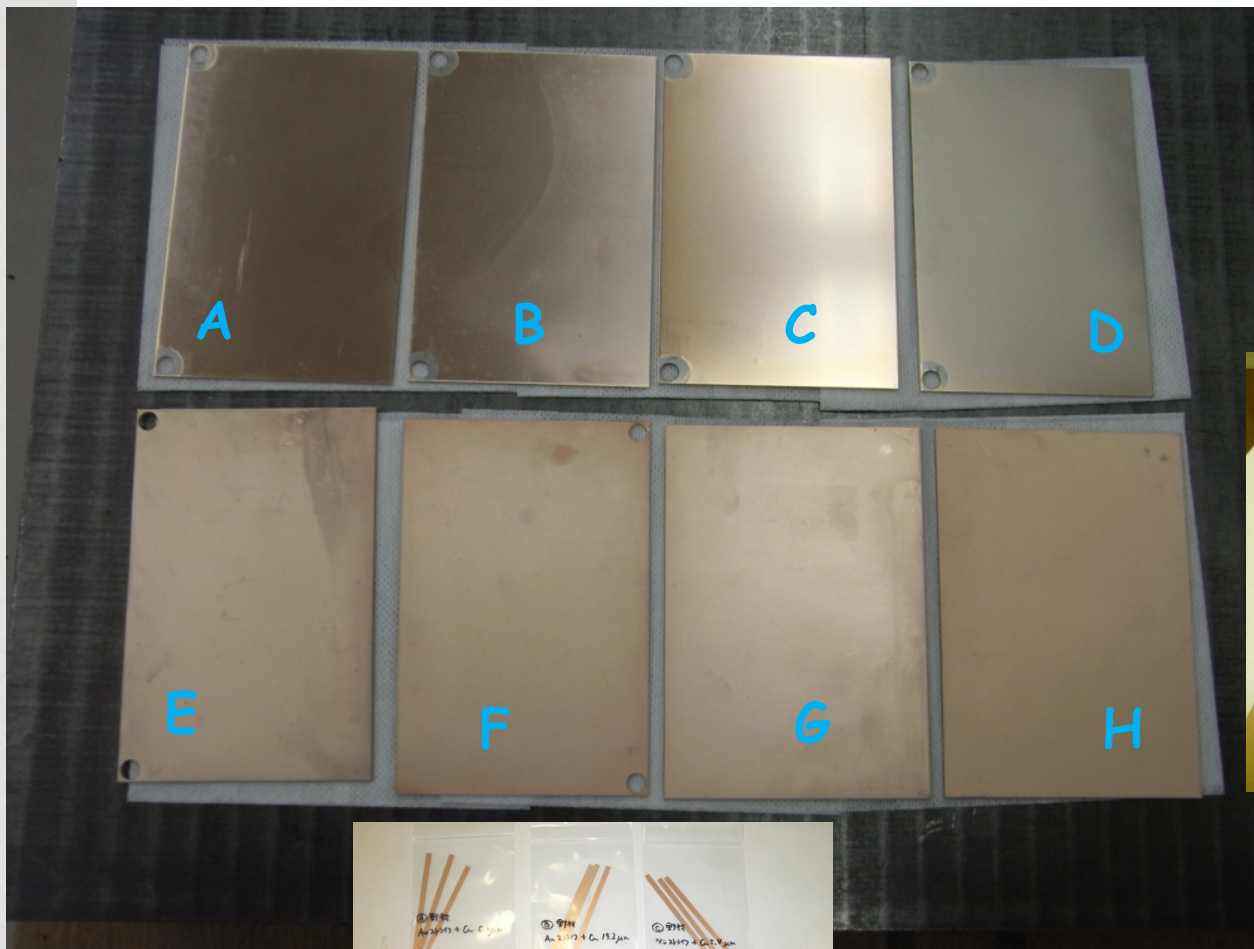


RRR measurement of Cu plating on KEK-STF2 couplers

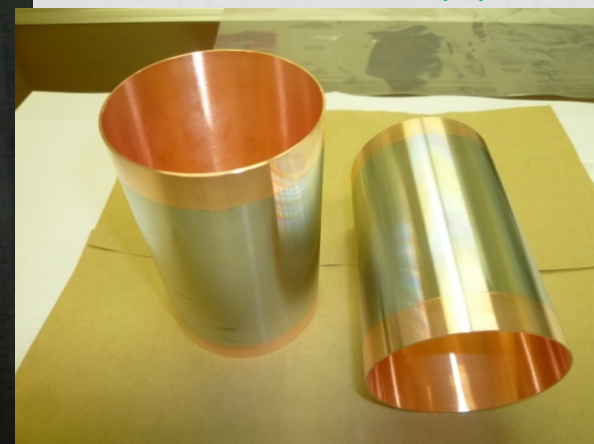
Eiji Kako (KEK, Japan)

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RRR measurement of Cu-plating samples



0.2 μm Au-strike
+ 3 μm Cu-plating
on 0.8t SUS pipe



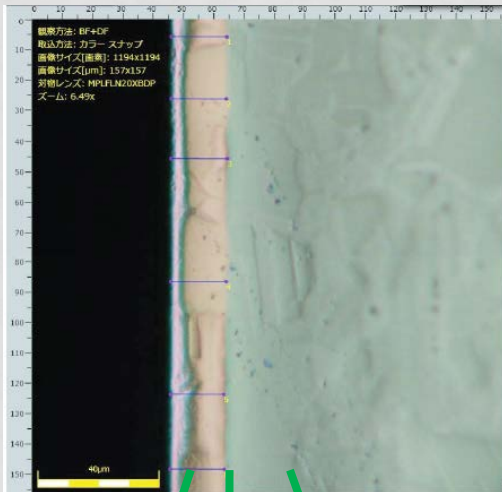
after anneal at 800 °C
in hydrogen furnace

RRR measurements of Cu-plating samples

Samples	(company)	Strike-plating	Cu-plating	Thickness of Cu	no anneal	after anneal
A	(N)	Ni	$\text{Cu}_2\text{P}_2\text{O}_7$	5 μm	A1, A2	A4, A5
B	(N)	Ni	$\text{Cu}_2\text{P}_2\text{O}_7$	20 μm	B1, B2	B4, B5
C	(N)	Au	$\text{Cu}_2\text{P}_2\text{O}_7$	5 μm	C1, C2	C4, C5
D	(N)	Au	$\text{Cu}_2\text{P}_2\text{O}_7$	20 μm	D1, D2	D4, D5
E	(T)	Ni	CuCN	5 μm	E1, E2	E4, E5
F	(T)	Ni	CuCN	20 μm	F1, F2	F4, F5
G	(F)	Ni	CuCN	10 μm	G1, G2	G4, G5
H	(F)	Ni	CuCN	35 μm	H1, H2	H4, H5

RRR measurements of Cu-plating samples

By H. Umezawa
(Tokyo-Denkai)



SUS 1.0t

Ni or Au
Strike plating
(0.2 μm)

Cu plating
(18 μm)

Thickness was measured
by digital microscope.

